

BC807-16/BC807-25/BC807-40

PNP TRANSISTOR



VOLTAGE: -45 Volts

POWER: 300 mW

SOT-23

Marking and Polarity

FEATURES

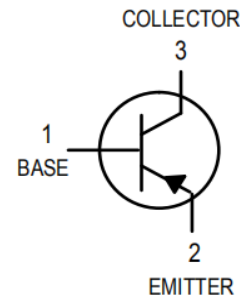
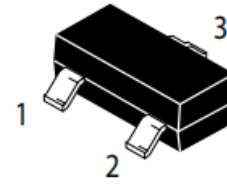
- Collector Current: IC=-0.5A
- Power Dissipation of 300mw

MECHANICAL DATA

- Package: SOT-23
- Epoxy UL: 94V-0
- Mounting position: Any
- Weight: approx. 0.01g

DEVICE MARKING

Device	Marking	H _{FE}
BC087-16	5A	100-250
BC087-25	5B	160-400
BC087-40	5C	250-600



Maximum Ratings (Ratings at 25°C ambient temperature unless otherwise specified.)

Parameter	Symbol	Value	Unit
Collector-Base Voltage)	V _{CBO}	-50	V
Collect-Emitter Voltage	V _{CEO}	-45	V
Emitter-Base Voltage	V _{EBO}	-5	V
Collector Current	I _c	-500	mA
Collector Power Dissipation	P _C	300	mW

Thermal Characteristics (Ratings at 25°C ambient temperature unless otherwise specified.)

Junction Temperature	T _J	-55 to 150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C
Typical thermal resistance	R _{θJA}	417	°C/W



SS8550

PNP TRANSISTOR



ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

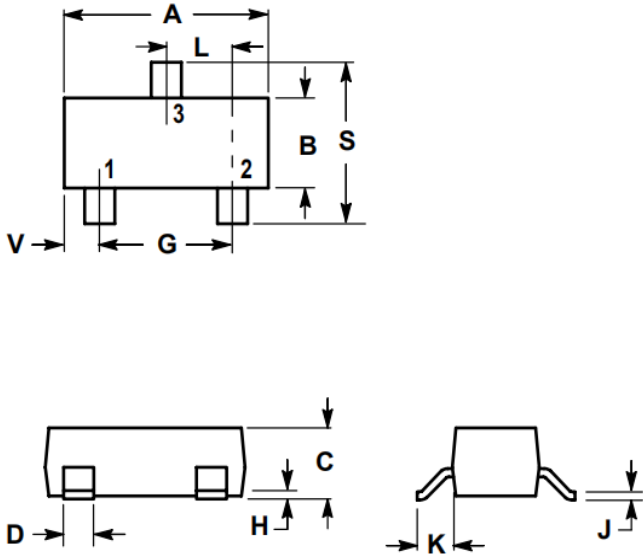
Characteristic	Test Condition	Symbol	Min.	Typ.	Max.	Unit
Collector-Emitter Breakdown Voltage	$I_C=-10\text{mA}, I_B=0$	$V_{(BR)CEO}$	-45	-	-	V
Collector-Base Breakdown Voltage	$I_C=-10\mu\text{A}, I_E=0$	$V_{(BR)CBO}$	-50	-	-	V
Emitter-Base Breakdown Voltage	$I_E=-1\mu\text{A}, I_C=0$	$V_{(BR)EBO}$	-5	-	-	V
Collector Cutoff Current	$V_{CB}=-45\text{V}, I_E=0$	I_{CBO}	-	-	-100	nA
Emitter Cutoff Current	$V_{EB}=-4\text{V}, I_C=0$	I_{EBO}	-	-	-100	μA
DC Current Gain	$V_{CE}=-1\text{V}, I_C=-100\text{mA}$	$H_{FE(1)}$	100	-	600	
	$V_{CE}=-1\text{V}, I_C=-500\text{mA}$	$H_{FE(2)}$	40	-	-	
Collector-Emitter Saturation Voltage	$I_C=-500\text{mA}, I_B=-50\text{mA}$	$V_{CE(Sat)}$	-	-	-0.7	V
Base-Emitter Saturation Voltage	$I_C=-500\text{mA}, I_B=-50\text{mA}$	$V_{BE(Sat)}$	-	-	-1.2	V
Transition Frequency	$V_{CE}=-5\text{V}, I_C=-10\text{mA}, f=100\text{MHz}$	F_T	100	-	-	MHz

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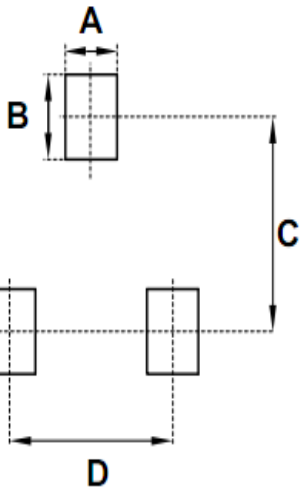
OUTLINE DRAWINGS



SOT-23

OUTLINE DIMENSIONS						
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.800	-	3.040	0.1102	-	0.1197
B	1.200	-	1.400	0.0472	-	0.0551
C	0.890	-	1.110	0.0350	-	0.0437
D	0.370	-	0.500	0.0146	-	0.0197
G	1.780	-	2.040	0.0701	-	0.0803
H	0.013	-	0.100	0.0005	-	0.0039
J	0.085	-	0.177	0.0033	-	0.0070
K	0.350	-	0.690	0.0138	-	0.0272
L	0.890	-	1.020	0.0350	-	0.0402
S	2.100	-	2.640	0.0827	-	0.1039
V	0.450	-	0.600	0.0177	-	0.0236

MOUNTING PAD LAYOUT



SOT-23

RECOMMENDED MOUNTING PAD DIMENSIONS						
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	0.600	-	-	0.0236	-
B	-	0.800	-	-	0.0315	-
C	-	2.020	-	-	0.0795	-
D	-	1.900	-	-	0.0748	-

PACKING INFORMATION

SOT-23

Package Method	Reel Size (mm)	Quantity (pcs/reel)	Inner Box Size LxWxH(mm)	Quantity (pcs/Inner Box)	Carton Size LxWxH(mm)	Quantity (pcs/carton)
Tape Reel	Φ180	3000	340x340x40	6000	364x364x360	160000

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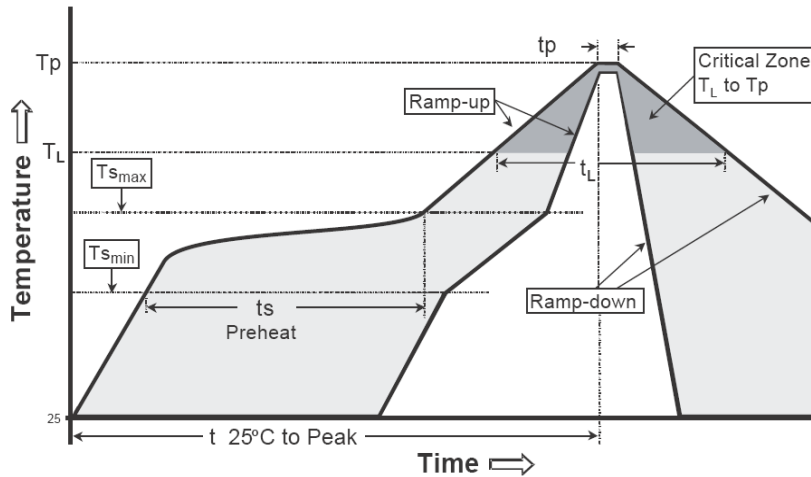


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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat -Temperature Min(T _{S min}) -Temperature Max(T _{S max}) -Time(t _{s min} to t _{s max})	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) - Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t _p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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